



Selds
Electronics, Defense, & Systems

Electronic Manufacturing Solutions

*Electronics Manufacturing Services - Systems Design Services - Repair and Reverse Engineering
Embedded Computers - Systems Engineering, Integration, and Simulation - Program Support*



Custom and Build to Print

- Design, Shared Development, Build-To-Print
- RF
- Microelectronics
- Mixed Technology Assemblies
- CCA
- Boards
- Cables and Harnesses
- Sub-Systems
- Prototype to Production Volume
- Testing

SELDS Inc. designs and manufactures high-density, high-reliability electronics for defense, medical, industrial, and commercial applications.

Our Electronic Manufacturing Solutions support prototype to production volumes for board, sub-system, and system manufacturing.

The electronic solutions provided by SELDS, Inc. can be found in demanding and hostile environments: military vehicles, defense systems, aircraft, medical and scientific equipment.

New product development, time-to-market, and time-to-production are critically important areas in today's global marketplace. To address this we establish strategic partnerships to meet product demands.

Delivery

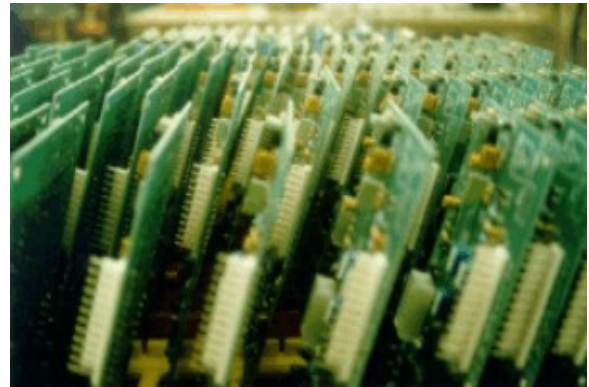
We provide solutions in a number of different ways to accommodate our customers' needs. Each delivery system has a common set deliverables and a custom set of deliverables which are project specific.

- Design: Complete product design and development from customer supplied Shared Development: Complete development from a customer supplied design with a focus on manufacturailibility and testability.
- Build-to-print: Complete turn-key manufacture from customer supplied production documents.



EMS Capabilities

- Surface Mount, Through Hole, or Mixed Technology Boards.
- Bonding, potting, and conformal coating
- Wire assembly for specialized cables and harnesses
- Electro-Mechanical assembly.
- Box Assembly and Integration
- Chassis Panel Assemblies
- **Surface Mount Technology**
Prototyping to Production quantities of Class 2 and Class 3 assemblies. Fine pitch to 12 mils. (BGA, uBGA, Flip chip, CSP, and chip components to 0402) Automatic Optical Solder Paste Inspector, 20 Zone reflow oven, SMT reflow and rework stations. Fine pitch and BGA rework stations.
- **Through Hole Technology**
Inline 18 inch wave soldering system, aqueous and no-clean fluxing, inline aqueous cleaning system. Conformal Coating of Acrylic, Polyester, Paralene, Silicone, and Polyurethane.
- **Quality Control and Testing**
ISO 9000 Quality System for Design and Production. All assemblies built to IPC-610C Class 2 or Class 3, J-STD-001. Fully automatic in-circuit functional testing, In Circuit Programming, Burn In, Environmental Testing, Bed- of - Nails testing, Testing programs developed from customer schematics



Boards



Precision Pick and Place

